

Product Change Notification / ALAN-277DF0664

	Pre Change	Post Change				
Pre and Post Change Summary:						
Description of Change: Qualification of MTAI as an additional final test location for selected AT24xx, AT25xx, and 24FCxx device families available in 8L UDFN (2x3x0.6mm) package.						
Microchip Parts Affected: Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)						
PCN Type:Manufacturing Char	nge					
PCN Status:Initial Notification						
Notification Text:						
ALAN-27ZDF0664_Affected_ ALAN-27ZDF0664_Affected_						
Affected CPNs:						
CCB 6183 Initial Notice: Qualif AT25xx, and 24FCxx device far		n additional final test location for selected AT24xx, UDFN (2x3x0.6mm) package.				
Notification Subject:						
Manufacturing Change						
PCN Type:						
Memory						
Product Category:						
29-May-2023						
Date:						

Final Test Location	Amkor Technology Philippine (P1/P2), INC. (ANAP)		Amkor Technology Philippine (P1/P2), INC. (ANAP)		Microchip Technology Thailand (HQ) (MTAI)		
Pin1 Orientation	Quad	rant 2	Quad	Quadrant 2		adrant 2	
BQM	5000	15000	5000	15000	5000	15000	
Carrier Tape	1	lo change.	e. See pre and post change for comparison.				
Cover Tape	Mir	nimal dime		ange. See pr omparison.	re and post c	hange for	
Plastic Reel	Minimal dimensional change. See pre and post change for comparison.				hange for		
Packing Method	Minimal dimensional change. See pre and post change for comparison.				hange for		

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve manufacturability by qualifying MTAI as an additional test location.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:June 2023

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

		Ма	ay 20	23			Jur	ne 20	23	
Workweek	1 8	1	2	2	2	23	24	25	26	27
Initial PCN Issue Date	0	,	0	ı	X					
Qual Report Availability						Х				

Final PCN Issue			V		
Date			Χ		

Method to Identify Change:Traceability code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: May 29, 2023: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_ALAN-27ZDF0664 Pre and Post Change.pdf PCN_ALAN-27ZDF0664 Qual_Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

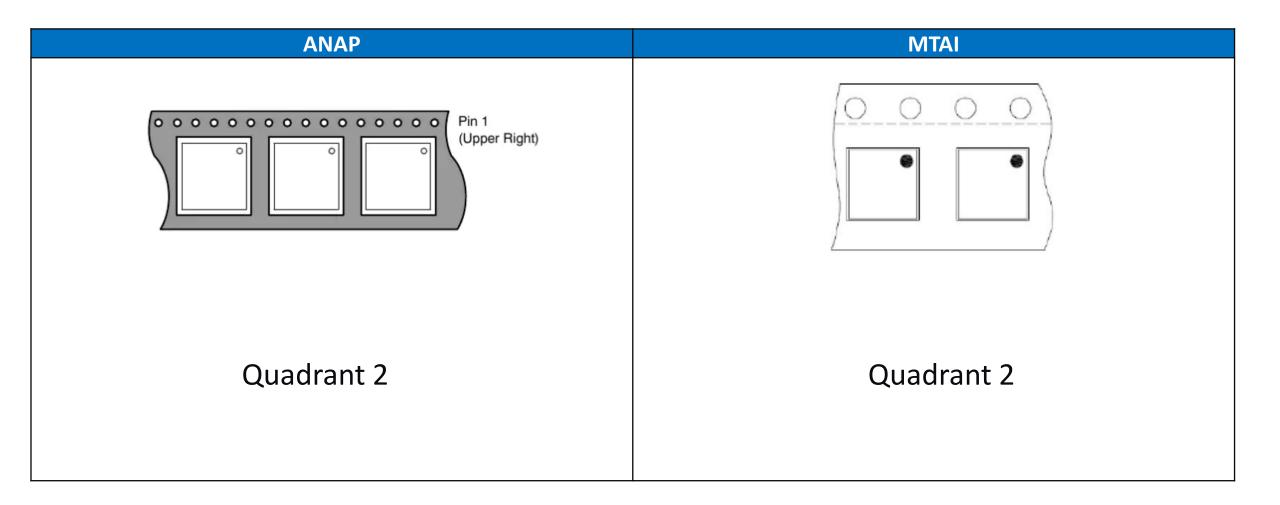
CCB 6183 Pre and Post Change Summary PCN# ALAN-27ZDF0664



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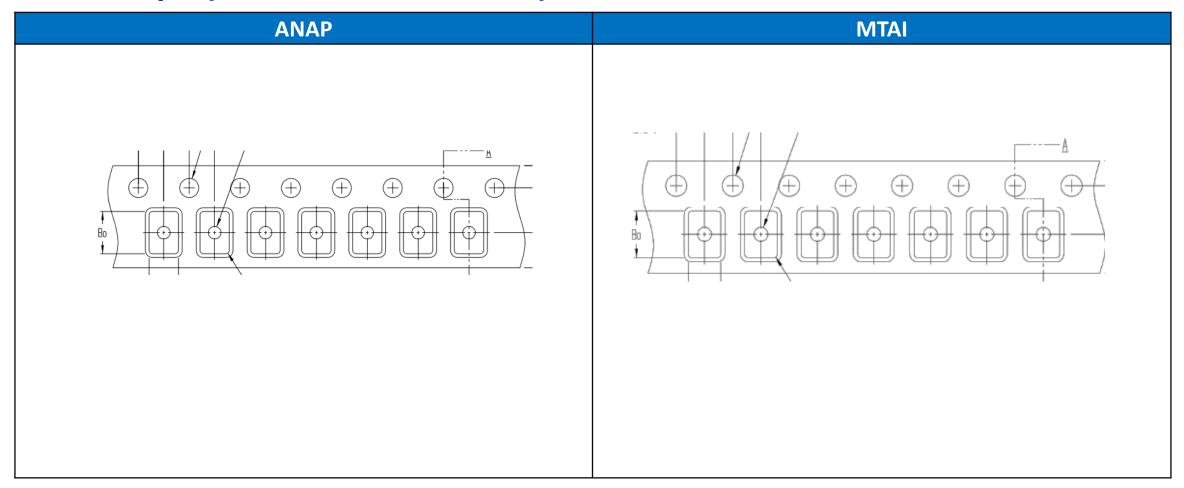


Pin1 Orientation Quadrant in Tape and Reel





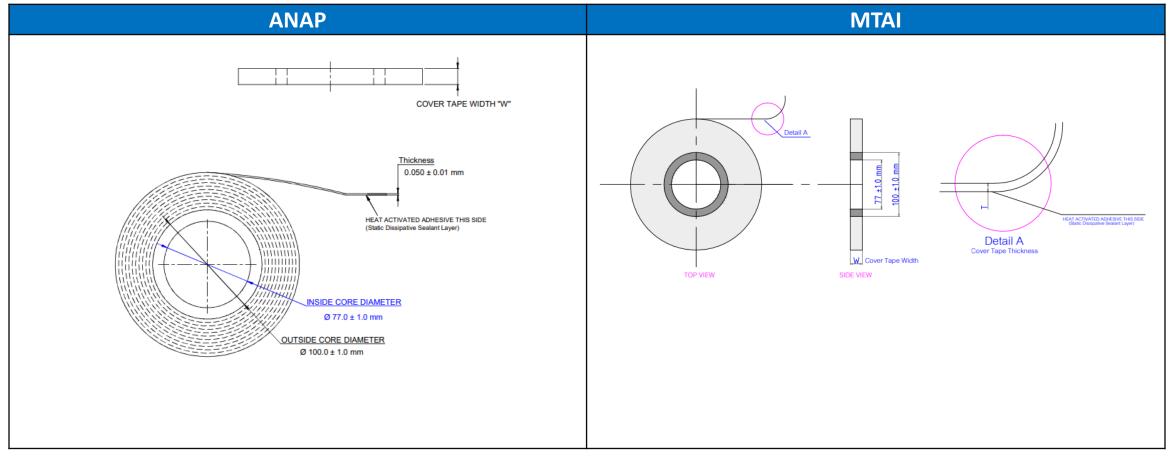
Carrier Tape (8L UDFN 2x3x0.6mm)



Plant	W (mm.)	P (mm.)	A0 (mm.)	B0 (mm.)	K0 (mm.)	Thickness (mm.)
ANAP	8.0 +0.3/-0.1	4.0 +/-0.1	2.30 +/- 0.1	3.30 +/- 0.1	0.75 +/- 0.1	0.30 +/-0.05
MTAI	8.00 +0.3/-0.1	4.00 ±0.1	2.30 ±0.1	3.30 ±0.1	0.75 ±0.1	0.30 ±0.05



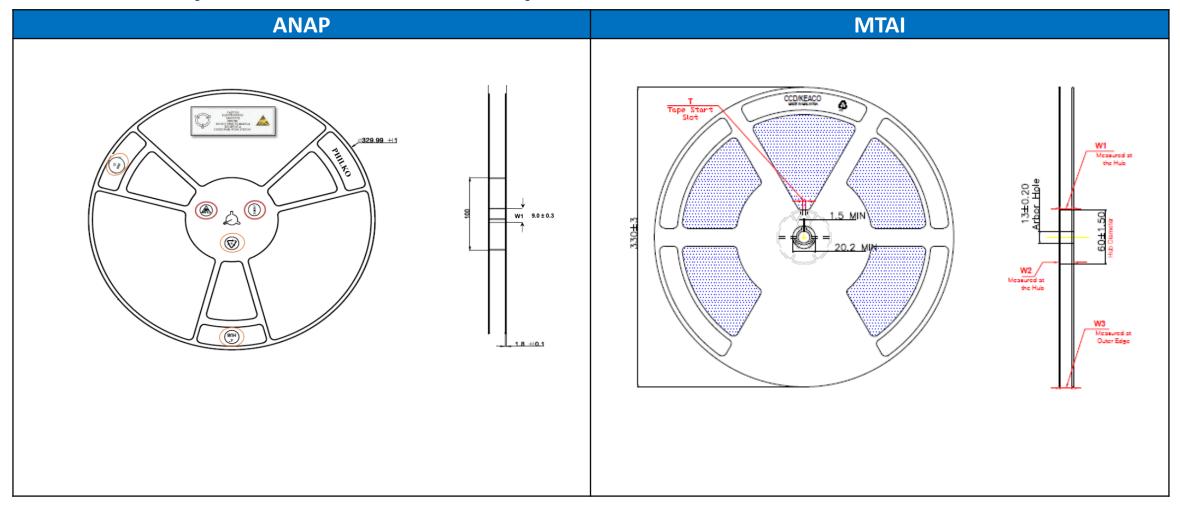
Cover Tape (8L UDFN 2x3x0.6mm)



Plant	Width W (mm.)	Thickness T (mm.)	Colour	Sealing Methodology
ANAP	5.4 +/- 0.10	0.050 +/- 0.01	Gray	Heat Seal
MTAI	5.3 ±0.1	0.050 ±0.010	Clear	Heat Seal



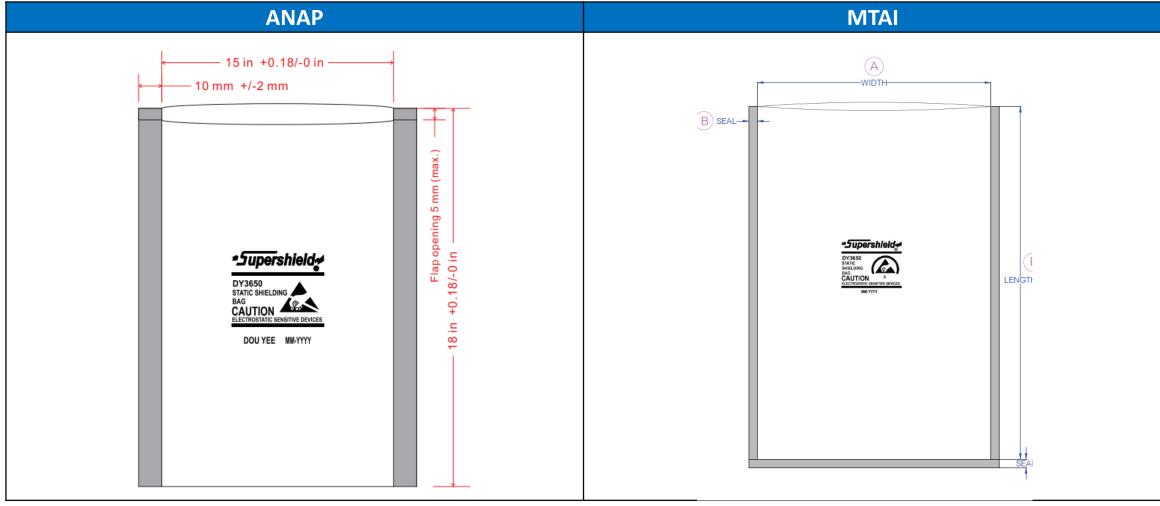
Plastic Reel (8L UDFN 2x3x0.6mm)



Plant	Supplier Part	Reel Diameter (mm.)	Reel Hub Size (mm)	Reel Width Max (mm.)	Colour
ANAP	PTC-PR0012-8	329.99 ±1	100	11.4 ±0.8	White
MTAI	91984-1	330 ±3.0	60 ±1.5	14.40	White



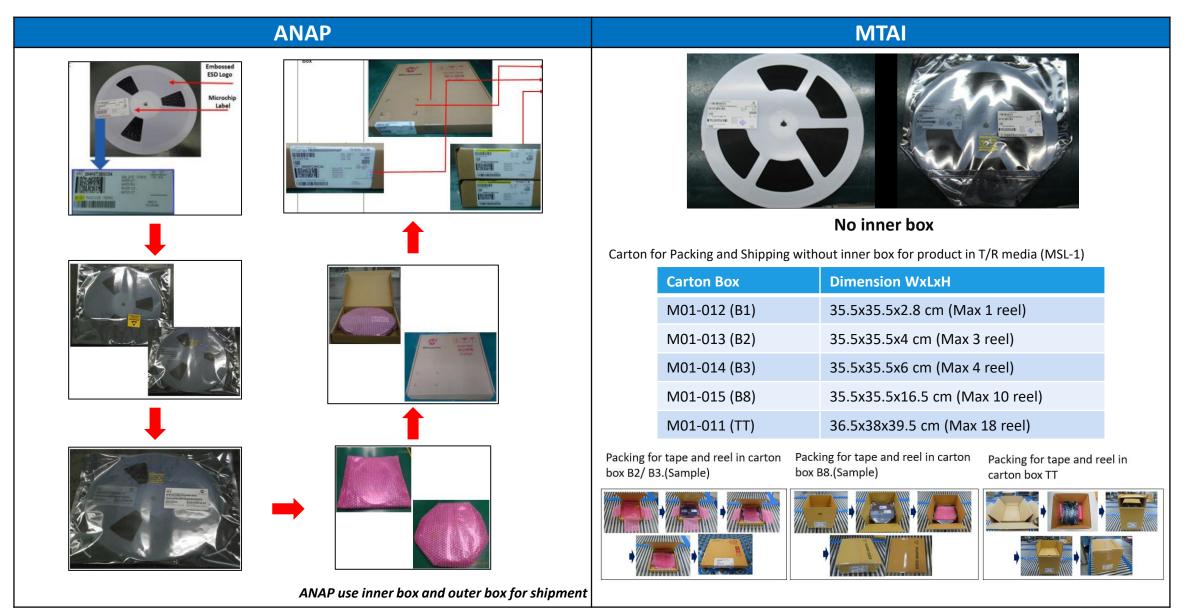
T/R Packing Static Sensitive Bag for Non dry Pack (MSL-1)



Plant	Length (mm)	Width (mm)	Thickness (mils)	Colour	
ANAP	482.6 +4.5/-0	381 +4.5/-0	3.0 +/- 0.3	Gray	
MTAI	420 +5/-0	370 +5/-0	3.0 ±0.3	Transparent	



T/R Packing Method for Non dry Pack (MSL-1)





ALAN-27ZDFO664 - CCB 6183 Initial Notice: Qualification of MTAI as an additional final test location for selected AT24xx, AT25xx, and 24FCxx device families available in 8L UDFN (2x3x0.6mm) package.

Affected Catalog Part Numbers (CPN)

AT24C256C-MAHL-T

AT24C16C-MAHDHP-T

AT25040B-MAHL-T

AT25040B-MAHL-E

AT25020B-MAHL-T

AT25020B-MAHL-E

AT25010B-MAHL-T

AT25010B-MAHL-E

AT34C02D-MAHM-T

AT34C02D-MAHM-E

AT24C04C-MAHM-E

AT24C04C-MAHM-T

AT24C512C-MAHM-T

AT24C512C-MAHM-E

AT24C08C-MAHM-T

AT24C08C-MAHM-E

AT24C01C-MAHM-T

AT24C01C-MAHM-E

AT24C02C-MAHM-T

AT24C02C-MAHM-E

AT24C256C-MAHL-E

AT24C16C-MAHM-T

AT24C16C-MAHM-E

AT24C64D-MAHM-T

AT24C64D-MAHM-E

AT24C128C-MAHM-T

AT24C128C-MAHM-E

AT24C32D-MAHM-T

AT24C32D-MAHM-E

AT25128B-MAHL-T

AT25128B-MAHL-E

AT25256B-MAHL-T

AT25256B-MAHL-E

AT25080B-MAHL-T

AT25080B-MAHL-E

AT25160B-MAHL-T

AT25160B-MAHL-E

AT25320B-MAHL-T AT25320B-MAHL-E

AT25640B-MAHL-T

AT25640B-MAHL-E

AT24C01D-MAHM-T

AT24C01D-MAHM-E

AT24C02D-MAHM-T

AT24C02D-MAHM-E

AT24C04D-MAHM-T

Date: Sunday, May 28, 2023

ALAN-27ZDFO664 - CCB 6183 Initial Notice: Qualification of MTAI as an additional final test location for selected AT24xx, AT25xx, and 24FCxx device families available in 8L UDFN (2x3x0.6mm) package. AT24C04D-MAHM-E AT24C08D-MAHM-T AT24C08D-MAHM-E AT24C16D-MAHM-T AT24C16D-MAHM-E AT24C32E-MAHM-T 24FC01T-I/MUY 24FC02T-I/MUY 24FC04T-I/MUY 24FC04HT-I/MUY 24FC01T-I/Q4B 24FC02T-I/Q4B 24FC04T-I/Q4B 24FC04HT-I/Q4B 24FC01T-E/MUY 24FC02T-E/MUY 24FC04T-E/MUY 24FC04HT-E/MUY 24FC01T-E/Q4B 24FC02T-E/Q4B 24FC04T-E/Q4B 24FC04HT-E/Q4B 24FC16T-I/MUY 24FC08T-I/MUY 24FC16T-I/Q4B 24FC08T-I/Q4B 24FC16T-E/MUY 24FC08T-E/MUY 24FC16T-E/Q4B 24FC08T-E/Q4B 24FC512T-I/Q4B 24FC512T-E/Q4B



QUALIFICATION PLAN SUMMARY RELIABILITY LABORATORY

PCN# ALAN-27ZDFO664

Date: May 27, 2023

Qualification of MTAI as an additional final test location for selected AT24xx, AT25xx, and 24FCxx device families available in 8L UDFN (2x3x0.6mm) package.



Qualification of MTAI as an additional final test location for **Purpose**

selected AT24xx, AT25xx, and 24FCxx device families available in 8L UDFN (2x3x0.6mm) package.

CCB 6183

Test	Condition
Test Correlation	 Build and test one wafer (> 3000 pcs.) for each of the 4 checkout products in MTAI Q4B package
	 Compare test yields from checkout in MTAI with ANAP yield trends.